L Number	Hits	Search Text	DB	Time stamp
-	17	"resist application" with semiconductor with substrate	USPAT; US-PGPUB	2004/06/15 14:18
-	1	("resist application" with semiconductor with substrate) and hmds	USPAT; US-PGPUB	2004/06/15 14:18
-	146	"resist application" with substrate	USPAT; US-PGPUB	2004/06/15 14:46
-	7	("resist application" with substrate) and hmds	USPAT; US-PGPUB	2004/06/15 14:18
-	21944	(resist or photoresist or "photo resist") with (applicat$4 or coat$3) with (substrate or wafer)	USPAT; US-PGPUB	2004/06/15 14:47
-	924	((resist or photoresist or "photo resist") with (applicat$4 or coat$3) with (substrate or wafer)) and hmds	USPAT; US-PGPUB	2004/06/15 14:47
-	4	(((resist or photoresist or "photo resist") with (applicat$4 or coat$3) with (substrate or wafer)) and hmds) and dehumidified	USPAT; US-PGPUB	2004/06/15 14:48
-	11	("5571560" | "5626913" | "5658615" | "5695817" | "5720814" | "5919520" | "5962070" | "5972426" | "6162507" | "6234692" | "6241403").PN.	USPAT	2004/06/16 08:29
-	3677	((427/240) or (427/314) or (427/444) or (438/782) or (438/780) or (438/905)).CCLS.	USPAT; US-PGPUB	2004/06/16 08:56
-	272	(((427/240) or (427/314) or (427/444) or (438/782) or (438/780) or (438/905)).CCLS.) and (((pre or preliminary) with (treatment or treating or treated)) or "pre-treatment" or "pretreatment")	USPAT; US-PGPUB	2004/06/16 09:01
-	8	(((427/240) or (427/314) or (427/444) or (438/782) or (438/780) or (438/905)).CCLS.) and ("de-humidified" or "dehumidified")	USPAT; US-PGPUB	2004/06/16 09:08
-	115	(((427/240) or (427/314) or (427/444) or (438/782) or (438/780) or (438/905)).CCLS.) and (humidity with (control$4 or reduc$4))	USPAT; US-PGPUB	2004/06/16 09:09
-	11	((((427/240) or (427/314) or (427/444) or (438/782) or (438/780) or (438/905)).CCLS.) and (((pre or preliminary) with (treatment or treating or treated)) or "pre-treatment" or "pretreatment")) and ((((427/240) or (427/314) or (427/444) or (438/782) or (438/780) or (438/905)).CCLS.) and (humidity with (control$4 or reduc$4)))	USPAT; US-PGPUB	2004/06/16 09:09
-	3	("5143552" | "6306455" | "6326597" | "2001/0044161" | "2002/0025375").PN.	USPAT	2004/06/16 10:20
-	3	("5143552" | "6306455" | "6326597" | "2001/0044161" | "2002/0025375").PN.	USPAT	2004/06/21 09:38
-	2	(resist or "photoresist") with (dehumidified or "humidity controll")	USPAT; US-PGPUB	2004/06/21 09:39
-	4	((resist or "photoresist") with (dehumidified or "humidity control")) and hmds	USPAT; US-PGPUB	2004/06/21 09:40
-	17	(resist or "photoresist") with (dehumidified or "humidity control")	USPAT; US-PGPUB	2004/06/21 09:44
-	2	(resist or "photoresist") with (dehumidified or "humidity control")	EPO; JPO	2004/06/21 09:46
-	13	(resist or "photoresist") and (dehumidified or "humidity control")	EPO; JPO	2004/06/21 09:46
-	11	("5571560" | "5626913" | "5658615" | "5695817" | "5720814" | "5919520" | "5962070" | "5972426" | "6162507" | "6234692" | "6241403").PN.	USPAT	2004/06/21 10:05
-	0	6458208.URPN.	USPAT	2004/06/21 10:26

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